AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A compositive laminate substrate, comprising:

at least an inorganic substrate having at least a passive component embedded therein;

two organic substrates integrated with the at least an inorganic substrate, having circuits for electrical connections between outer input/output ports and said passive component of said inorganic substrate through said organic substrates; and

at least one bonding layer having vias formed therein, for bonding said inorganic substrate and said organic substrate.

2. (Original) The compositive laminate substrate according to claim 1 wherein the material of said inorganic substrate is selected from the group consisting of ceramic, silicon and glass.

3. (Previously Presented) The compositive laminate substrate according to claim 2 wherein when said inorganic substrate is ceramic material, said passive component is made from the process selected from the group consisting of thick film process and thin film process.

4. (Previously Presented) The compositive laminate substrate according to claim 2 wherein said inorganic substrate is silicon material, said passive component is made from a semiconductor fabrication process.

5. (Original) The compositive laminate substrate according to claim 1 wherein said passive component is selected from the group consisting of capacitor, inductor and resistor.

6. (Original) The compositive laminate substrate according to claim 1 wherein each of said organic substrate is composed of a plurality of print circuit boards.

7. (Original) The compositive laminate substrate according to claim 6 wherein the circuit of the print circuit boards are made separately, and then stacked together to form said organic substrates.

8. (Original) The compositive laminate substrate according to claim 6 wherein the circuit of the print circuit boards are made separately, then stack the print circuit boards together, and finally form the circuit of a surface layer with build-up process to form said organic substrates.

9. (Original) The compositive laminate substrate according to claim 1 wherein at least one of said organic substrate further comprises at least a passive component.

10. (Original) The compositive laminate substrate according to claim 9 wherein said passive component on said organic substrate is selected from the group consisting of capacitor, inductor and resistor.

11. (Original) The compositive laminate substrate according to claim 1 wherein said organic substrate is made on said inorganic substrate with build-up process.

12. – 13. (Cancelled)

14. (Previously Presented) The compositive laminate substrate, comprising:

an inorganic substrate having at least a passive component formed thereon;

an organic substrate, integrated with the inorganic substrate, having circuits for electrical connections between outer input/output ports and said passive component on said inorganic substrate; and

a bonding layer having vias formed therein, for bonding said inorganic substrate and said organic substrate.

15. (Original) The compositive laminate substrate according to claim 14 wherein material of said inorganic substrate is selected from the group consisting of ceramic, silicon and glass.

16. (Previously Presented) The compositive laminate substrate according to claim 15 wherein when said inorganic substrate is ceramic material, said passive component is made from a process selected from the group consisting of thick film process and thin film process.

17. (Previously Presented) The compositive laminate substrate according to claim 15 wherein when said inorganic substrate is silicon material, said passive component is made from a semiconductor fabrication process.

18. (Original) The compositive laminate substrate according to claim 14 wherein said passive component is selected from the group consisting of capacitor, inductor and resistor.

19. (Original) The compositive laminate substrate according to claim 14 wherein said organic substrate is composed of a plurality of print circuit boards.

20. (Original) The compositive laminate substrate according to claim 19 wherein the circuit of said print circuit boards of said organic substrate are made separately, and then stacked together to form said organic substrate.

21. (Original) The compositive laminate substrate according to claim 19 wherein the circuit of said print circuit boards of said organic substrate are made separately, then stack the print circuit boards together, and finally form the circuit of a surface layer with build-up process to form said organic substrate.

22. (Original) The compositive laminate substrate according to claim 14 wherein said organic substrate further comprises at least a passive component.

23. (Previously Presented) The compositive laminate substrate according to claim 22 wherein said passive component on said organic substrate is selected from the group consisting of capacitor, inductor and resistor.

24. (Original) The compositive laminate substrate according to claim 14 wherein said organic substrate is made on said inorganic substrate with build-up process.

25. (Cancelled)

26. (Currently Amended) A compositive laminate substrate, comprising:

at least an inorganic substrate having at least a passive component embedded therein;

two organic substrates, integrated with said at least an inorganic substrate, having circuits for electrical connections between outer input/output ports and said passive component of said inorganic substrate through said organic substrates; and

a covering layer, for covering said inorganic substrate ~~being embedded therein~~and, ~~integrating with~~bonding to said organic substrate such that said inorganic substrate covered by said covering layer is integrated between said organic substrates, said covering layer further comprising circuits for providing electrical connections between said passive component and said organic substrate.

27. (Previously Presented) The compositive laminate substrate according to claim 26 wherein the material of said inorganic substrate is selected from the group consisting of ceramic, silicon and glass.

28. (Previously Presented) The compositive laminate substrate according to claim 27 wherein when said inorganic substrate is ceramic material, said passive component is made from the process selected from the group consisting of thick film process and thin film process.

29. (Previously Presented) The compositive laminate substrate according to claim 27 wherein said inorganic substrate is silicon material, said passive component is made from a semiconductor fabrication process.

30. (Previously Presented) The compositive laminate substrate according to claim 26 wherein said passive component is selected from the group consisting of capacitor, inductor and resistor.

31. (Previously Presented) The compositive laminate substrate according to claim 26 wherein each of said organic substrate is composed of a plurality of print circuit boards.

32. (Previously Presented) The compositive laminate substrate according to claim 31 wherein the circuit of the print circuit boards are made separately, and then stacked together to form said organic substrates.

33. (Previously Presented) The compositive laminate substrate according to claim 31 wherein the circuit of the print circuit boards are made separately, then stack the print circuit boards together, and finally form the circuit of a surface layer with build-up process to form said organic substrates.

34. (Previously Presented) The compositive laminate substrate according to claim 26 wherein at least one of said organic substrate further comprises at least a passive component.

35. (Previously Presented) The compositive laminate substrate according to claim 34 wherein said passive component on said organic substrate is selected from the group consisting of capacitor, inductor and resistor.

36. (Previously Presented) The compositive laminate substrate according to claim 26 wherein said organic substrate is made on said inorganic substrate with build-up process.